## **Panasonic**

# **MA21D34**

## Silicon epitaxial planar type

#### For rectification

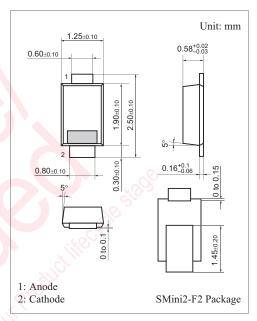
#### ■ Features

- Forward current (Average)  $I_{F(AV)} = 1.0 \text{ A}$  rectification is possible
- Low forward voltage V<sub>F</sub>

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Maximum peak reverse voltage	$V_{RM}$	30	V
Forward current (Average)	I <sub>F(AV)</sub>	1.0	A
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	20	A
Junction temperature	$T_{j}$	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

Note) \*: 50 Hz sine wave 1 cycle (Non-repetitive peak current)



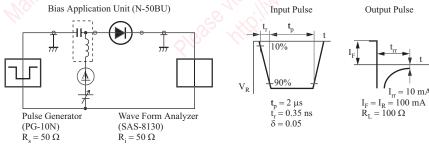
Marking Symbol: 4V

### ■ Electrical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions Min	Тур	Max	Unit
Forward voltage $V_{F1}$ $V_{F2}$	$V_{Fl}$	$I_F = 0.7 A$	0.33	0.36	N/
	$I_F = 1.0 \text{ A}$	0.35	0.38	<b>V</b>	
Reverse current	$I_R$	$V_R = 30 \text{ V}$	10.	1 200	μΑ
Terminal capacitance	$C_{t}$	$V_R = 10 \text{ V, } f = 1 \text{ MHz}$	45		pF
Reverse recovery time *	$t_{rr}$	$I_F = I_R = 100 \text{ mA}, I_{\pi} = 10 \text{ mA},$ $R_L = 100 \Omega$	14		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. \*: t<sub>rr</sub> measurement circuit



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